

PATENT APPLICATION *IFW*

IN THE U.S. PATENT AND TRADEMARK OFFICE

August 7, 2008

Applicants: Atsushi YABE et al

Title: ELECTROLESS COPPER PLATING SOLUTION

Serial No.: 10/576 231

Group: 1792

Confirmation No.: 7188

Filed: April 14, 2006

Examiner: Bareford

International Application No.: PCT/JP2004/011327

International Filing Date: July 30, 2004

Atty. Docket No.: 4700.P0327US

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

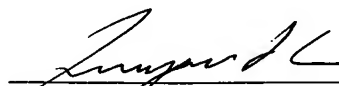
☐ Applicant claims small entity status. See 37 CFR 1.27.☐ The additional filing fee has been calculated as shown below:

For	No. Filed	No. Extra	(X) LG Entity	RATE	() SM Entity	Fee
Total Claims	(4 - 20 = 0)		x \$ 50.00		x \$ 25.00	
Indep. Claims	(1 - 3 = 0)		x \$210.00		x \$105.00	
[] Multiple Dep. Claim			+ \$370.00		+ \$185.00	
* * * TOTAL FILING FEE * * *						\$ 0.00

☐ Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.☐ A Check for \$ is enclosed to cover fees.☒ Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

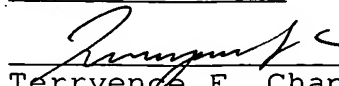
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TFC/smd


Terryence F. Chapman Reg. No. 32 549-----
CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on August 7, 2008.

130.09/07


Terryence F. Chapman



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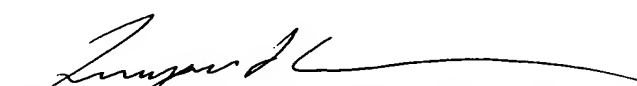
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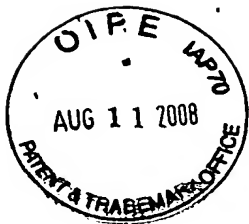

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P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

Sir:

In response to the Office Action dated May 9, 2008,
please amend the above-identified application as follows:
(Please see following pages.)

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I hereby certify that this correspondence is being
deposited with the United States Postal Service with
sufficient postage as first class mail in an envelope
addressed to: Commissioner for Patents, P.O. Box 1450,
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Terryence F. Chapman